

M HI1206T500R-10

UNCONTROLLED

PHYSICAL DIMENSIONS:

A 3.20 [.126] ± 0.20 [.008]

B 1.60 [.063] ± 0.20 [.008]

C 1.10 [.043] ± 0.20 [.008]

D 0.51 [.020] ± 0.25 [.010]

ELECTRICAL CHARACTERISTICS:			
Z @ 100MHz (Ω)		DCR (\(\Omega\)	Rated Current
Nominal	50		
Minimum	38		
Maximum	63	0.010	6000 mA

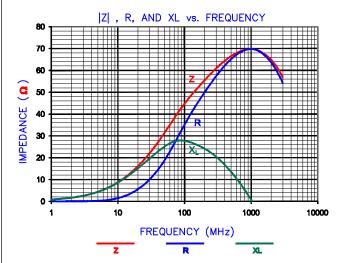
NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL.
- 2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 3. TERMINATION FINISH IS 100% TIN.

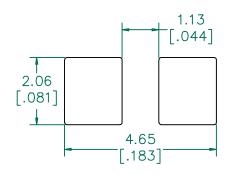
80 70 0amp 60 1amp 50 · 2amp - 3amp 4amp 5amp 1000 FREQUENCY (MHz)

Z vs. FREQUENCY

IMPEDANCE UNDER DC BIAS



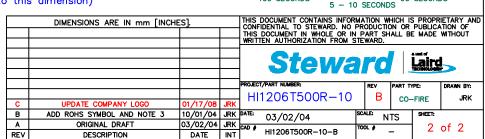
LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 [.030] to this dimension)

REFLOW SOLDERING PRE-HEATING 9 130 [266] 60 SECONDS

RECOMMENDED SOLDERING CONDITIONS



100 SECONDS

AGILENT E4991A RF Impedance/Material Analyzer HP 16092A Test Fixture. TEST REF. 3185